# CLAIMS

[Claim 1]

A resin composition comprising:

(A) a thermosetting resin;

(B) a polymer having a hydrocarbon chain or a polyether chain;

(X) a phosphorus compound-based flame retardant; and

(Y) a flame retardant other than the phosphorus compound-based flame retardant,

wherein the component (X) does not contain (X1) a filler-type flame retardant, and the component (Y) does not contain (Y1) a filler-type flame retardant, or,

wherein when the component (X) contains the filler-type flame retardant (X1) or the component (Y) contains the filler-type flame retardant (Y1), a total content of the filler-type flame retardant (X1) and the filler-type retardant (Y1) is 25 parts by mass or less with respect to 100 parts by mass of a solid content in the resin composition.

[Claim 2]

The resin composition according to claim 1,

wherein the component (X) contains (X2) a compatible flame retardant.

[Claim 3]

The resin composition according to claim 1 or 2,

wherein the component (Y) contains (Y2) a compatible flame retardant.

[Claim 4]

The resin composition according to any one of claims 1 to 3,

wherein the component (A) contains at least one selected from the group consisting of an epoxy resin, a maleimide compound, a phenol resin, a polyimide resin, a cyanate resin, an isocyanate resin, a benzoxazine resin, an oxetane resin, an amino resin, an unsaturated polyester resin, an allyl resin, a dicyclopentadiene resin, a silicone resin, a triazine resin, and a melamine resin.

[Claim 5]

The resin composition according to any one of claims 1 to 4,

wherein the component (B) is at least one selected from the group consisting of a conjugated diene polymer, a styrene-based elastomer, and a modified product thereof.

[Claim 6]

The resin composition according to any one of claims 1 to 5,

wherein the component (X) contains at least one selected from the group consisting of (X-i) a phosphate compound, (X-ii) a phosphine oxide compound, (X-iii) a phosphaphenanthrene compound, (X-iv) a metal salt of phosphinic acid, and (X-v) a nitrogen-containing organic phosphorus compound.

[Claim 7]

The resin composition according to any one of claims 1 to 6,

wherein the component (X) contains two or more phosphorus atoms in one molecule.

[Claim 8]

The resin composition according to any one of claims 1 to 7,

wherein the component (Y) is a halogen-based flame retardant.

[Claim 9]

The resin composition according to any one of claims 1 to 8, further comprising:

(C) an inorganic filler.

[Claim 10]

The resin composition according to any one of claims 1 to 9, further comprising:

(D) a curing accelerator.

[Claim 11]

A prepreg comprising:

the resin composition according to any one of claims 1 to 10; or

a semi-cured product of the resin composition.

[Claim 12]

A resin film comprising:

the resin composition according to any one of claims 1 to 10; or

a semi-cured product of the resin composition.

[Claim 13]

A laminate comprising:

a cured product of the resin composition according to any one of claims 1 to 10; or
a cured product of the prepreg according to claim 11; and
a metal foil.

[Claim 14]

A printed wiring board comprising:
a cured product of the resin composition according to any one of claims 1 to 10.

[Claim 15]

A semiconductor package comprising:
the printed wiring board according to claim 14; and
a semiconductor element.